Features

- No External Components Except PIN Diode
- Supply-voltage Range: 2.7V to 5.5V
- Highest Sensitivity Due to Automatic Sensitivity Adaption (AGC) and Automatic Strong Signal Adaption (ATC)
- Automatic Supply Voltage Adaptation
- · Highest Immunity against Disturbances from Daylight and Lamps
- Available for Carrier Frequencies between 30 kHz to 76 kHz; adjusted by Zener-Diode Fusing ±2.5%
- TTL and CMOS Compatible

Applications

- Home Entertainment Applications (Audio/Video)
- Home Appliances
- Remote Control Equipment

1. Description

The IC T2526 is a complete IR receiver for data communication developed and optimized for use in carrier-frequency-modulated transmission applications. The IC offers highest sensitivity as well as highest suppression of noise from daylight and lamps. The T2526 is available with broadest range of frequencies (30, 33, 36, 37, 38, 40, 44, 56, 76 kHz) and 5 different noise suppression regulation types (standard, lamp, noise, short burst, data rate) covering requirements of high-end remote control solutions (please refer to selection guide available for T2525/T2526). The T2526 operates in a supply voltage range of 2.7V to 5.5V.

The function of the T2526 can be described using the block diagram of Figure 1-1 on page 2. The input stage meets two main functions. First it provides a suitable bias voltage for the PIN diode. Secondly the pulsed photo-current signals are transformed into a voltage by a special circuit which is optimized for low noise applications. After amplification by a Controlled Gain Amplifier (CGA) the signals have to pass a tuned integrated narrow bandpass filter with a center frequency f_0 which is equivalent to the chosen carrier frequency of the input signal The demodulator is used first to convert the input burst signal to a digital envelope output pulse and to evaluate the signal information quality, i.e., unwanted pulses will be suppressed at the output pin. All this is done by means of an integrated dynamic feedback circuit which varies the gain as a function of the present environmental conditions (ambient light, modulated lamps etc.). Other special features are used to adapt to the current application to secure best transmission quality.



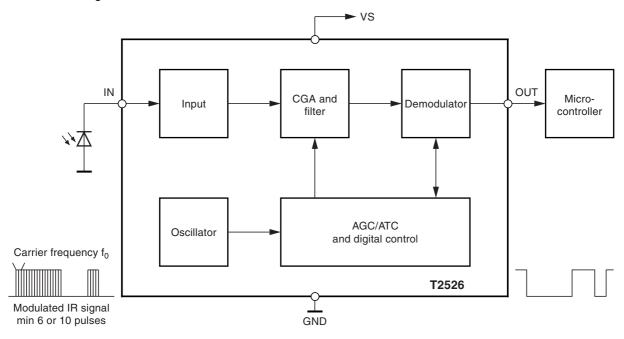
Low-voltage IR Receiver ASSP

T2526





Figure 1-1. Block Diagram



2. Pin Configuration

Figure 2-1. Pinning TSSOP8

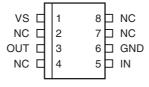


Table 2-1. Pin Description

Pin	Symbol	Function
1	VS	Supply voltage
2	NC	Not connected
3	OUT	Data output
4	NC	Not connected
5	IN	Input PIN-diode
6	GND	Ground
7	NC	Not connected
8	NC	Not connected

3. Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Parameter	Symbol	Value	Unit
Supply voltage	V _S	-0.3 to +6	V
Supply current	I _S	3	mA
Input voltage	V _{IN}	-0.3 to $V_{\rm S}$	V
Input DC current at V _S = 5V	I _{IN}	0.75	mA
Output voltage	V _O	-0.3 to $V_{\rm S}$	V
Output current	Io	10	mA
Operating temperature	T _{amb}	-25 to +85	°C
Storage temperature	T _{stg}	-40 to +125	°C
Power dissipation at T _{amb} = 25°C	P _{tot}	30	mW

4. Thermal Resistance

Parameters	Symbol	Value	Unit
Junction ambient TSSOP8	R_{thJA}	TBD	K/W





5. Electrical Characteristics, 3-V Operation

 $T_{amb} = 25$ °C, $V_S = 3V$ unless otherwise specified.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Тур.	Max.	Unit	Type*
1	Supply								
1.1	Supply-voltage range		1	Vs	2.7	3.0	3.3	V	С
1.2	Supply current	I _{IN} =0	1	I _S	0.7	0.9	1.3	mA	В
2	Output								
2.1	Internal pull-up resistor ⁽¹⁾	T _{amb} = 25°C See Figure 7-10 on page 10	1, 3	R _{PU}		30/40		kΩ	А
2.2	Output voltage low	$R_2 = 2.4 \text{ k}\Omega$ See Figure 7-10 on page 10	3, 6	V _{OL}			250	mV	В
2.3	Output voltage high		3, 1	V _{OH}	V _S - 0.25		Vs	V	В
2.4	Output current clamping	R ₂ = 0 See Figure 7-10 on page 10	3, 6	I _{OCL}		8		mA	В
3	Input	,		•	1			•	•
3.1	Input DC current	V _{IN} = 0 See Figure 7-10 on page 10	5	I _{IN_DCMAX}	-150			μΑ	С
3.2	Input DC current See Figure 7-3 on page 7	$V_{IN} = 0$; $Vs = 3V$ $T_{amb} = 25$ °C	5	I _{IN_DCMAX}		-350		μΑ	В
3.3	Minimum detection threshold current See Figure 7-1 on page 7	Test signal: See Figure 7-9 on page 10 V _S = 3V	3	I _{Eemin}		-700		pA	В
3.4	Minimum detection threshold current with AC current disturbance IIN_AC100 = 3 µA at 100 Hz	T_{amb} = 25°C, I_{IN_DC} =1 μA square pp burst N = 16 f = f ₀ ; t _{PER} = 10 ms Figure 7-8 on page 9 BER = 50 ⁽²⁾	3	I _{Eemin}		-1300		pA	С
3.5	Maximum detection threshold current with V_{IN} > 0V	Test signal: See Figure 7-9 on page 10 $V_S = 3V$, $T_{amb} = 25^{\circ}C$ $I_{IN_DC} = 1 \mu A$ square pp burst $N = 16$ $f = f_0$; $t_{PER} = 10 \text{ ms}$ Figure 7-8 on page 9 BER = $5\%^{(2)}$	3	I _{Eemax}	-200			μА	D

^{*)} Type means: A =100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Notes: 1. Depending on version, see "Ordering Information"

^{2.} BER = bit error rate; e.g., BER = 5% means that with P = 20 at the input pin 19...21 pulses can appear at the pin OUT

^{3.} After transformation of input current into voltage

5. Electrical Characteristics, 3-V Operation (Continued)

 $T_{amb} = 25$ °C, $V_S = 3V$ unless otherwise specified.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Тур.	Max.	Unit	Type*
4	Controlled Amplifier and Filter								
4.1	Maximum value of variable gain (CGA)			G _{VARMAX}		51		dB	D
4.2	Minimum value of variable gain (CGA)			G _{VARMIN}		-5		dB	D
4.3	Total internal amplification ⁽³⁾			G _{MAX}		71		dB	D
4.4	Center frequency fusing accuracy of bandpass	V _S = 3V, T _{amb} = 25°C		f _{03V_FUSE}	-2.5	f ₀	+2.5	%	Α
4.5	Overall accuracy center frequency of bandpass			f _{03V}	-5.5	f ₀	+3.5	%	С
4.6	Overall accuracy center frequency of bandpass	T _{amb} = 0 to 70°C		f _{03V}	-4.5	f ₀	+3.0	%	С
4.7	BPF bandwidth	-3 dB; $f_0 = 38$ kHz; See Figure 7-7 on page 9		В		3.8		kHz	С

^{*)} Type means: A =100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Notes: 1. Depending on version, see "Ordering Information"

3. After transformation of input current into voltage

6. Electrical Characteristics, 5-V Operation

 $T_{amb} = 25$ °C, $V_S = 5V$ unless otherwise specified.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Тур.	Max.	Unit	Type*
5	Supply								
5.1	Supply-voltage range		1	V _S	4.5	5.0	5.5	V	С
5.2	Supply current	I _{IN} =0	1	I _S	0.9	1.2	1.6	mA	В
6	Output			•				•	•
6.1	Internal pull-up resistor ⁽¹⁾	T _{amb} = 25°C See Figure 7-10 on page 10	1, 3	R _{PU}		30/40		kΩ	А
6.2	Output voltage low	$R_2 = 2.4 \text{ k}\Omega$ See Figure 7-10 on page 10	3, 6	V _{OL}			250	mV	В
6.3	Output voltage high		3, 1	V _{OH}	$V_{S} - 0.25$		Vs	V	В
6.4	Output current clamping	R ₂ = 0 See Figure 7-10 on page 10	3, 6	I _{OCL}		8		mA	В

^{*)} Type means: A =100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Notes: 1. Depending on version, see "Ordering Information"

- 2. BER = bit error rate; e.g., BER = 5% means that with P = 20 at the input pin 19...21 pulses can appear at the pin OUT
- 3. After transformation of input current into voltage



^{2.} BER = bit error rate; e.g., BER = 5% means that with P = 20 at the input pin 19...21 pulses can appear at the pin OUT



6. Electrical Characteristics, 5-V Operation (Continued)

 $T_{amb} = 25$ °C, $V_S = 5V$ unless otherwise specified.

No.	Parameters	Test Conditions Pin Symbol Min. Typ.		Тур.	Max.	Unit	Type*		
7	Input								
7.1	Input DC current	V _{IN} = 0 See Figure 7-10 on page 10	5	I _{IN_DCMAX}	-400			μΑ	С
7.2	Input DC-current See Figure 7-4 on page 8	V _{IN} = 0; Vs = 5V T _{amb} = 25°C	5	I _{IN_DCMAX}		-700		μΑ	В
7.3	Min. detection threshold current See Figure 7-2 on page 7	T _{amb} = 25°C	3	I _{Eemin}		-850		pА	В
7.4	Min. detection threshold current with AC current disturbance IIN_AC100 = 3 μA at 100 Hz	I_{IN_DC} = 1 μA square pp burst N = 16 f = f ₀ ; t _{PER} = 10 ms Figure 7-8 on page 9 BER = 50 ⁽²⁾	3	I _{Eemin}		-2000		pA	С
7.5	Max. detection threshold current with V _{IN} > 0V	Test signal: See Figure 7-9 on page 10 $V_S = 5V$, $T_{amb} = 25^{\circ}$ C $I_{IN_DC} = 1$ μ A square pp burst $N = 16$ $f = f_0$; $t_{PER} = 10$ ms Figure 7-8 on page 9 BER = $5\%^{(2)}$	3	I _{Eemax}	-500			μΑ	D
8	Controlled Amplifier a	nd Filter							
8.1	Maximum value of variable gain (CGA)			G _{VARMAX}		51		dB	D
8.2	Minimum value of variable gain (CGA)			G _{VARMIN}		- 5		dB	D
8.3	Total internal amplification ⁽³⁾			G _{MAX}		71		dB	D
8.4	Resulting center frequency fusing accuracy	f_0 fused at $V_S = 3V$ $V_S = 5V$, $T_{amb} = 25$ °C		f _{05V}		f _{03V-FUSE} + 0.5		%	А

^{*)} Type means: A =100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Notes: 1. Depending on version, see "Ordering Information"

- 2. BER = bit error rate; e.g., BER = 5% means that with P = 20 at the input pin 19...21 pulses can appear at the pin OUT
- 3. After transformation of input current into voltage

6.1 **ESD**

All pins ⇒2000V HBM; 200V MM, MIL-STD-883C, Method 3015.7

6.2 Reliability

Electrical qualification (1000h) in molded plastic package

7. Typical Electrical Curves at T_{amb} = 25°C

Figure 7-1. I_{Eemin} versus I_{IN_DC} , $V_S = 3V$

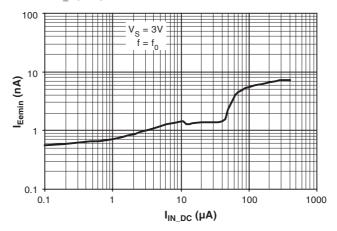


Figure 7-2. I_{Eemin} versus I_{IN_DC} , $V_S = 5V$

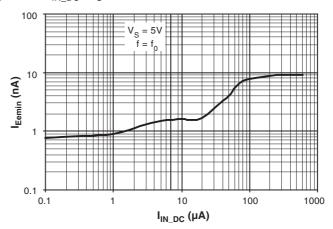


Figure 7-3. V_{IN} versus I_{IN_DC} , $V_S = 3V$

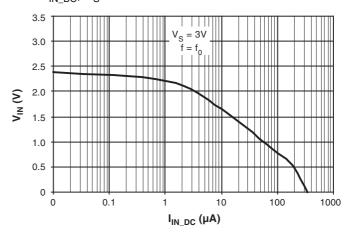






Figure 7-4. V_{IN} versus I_{IN_DC} , $V_S = 5V$

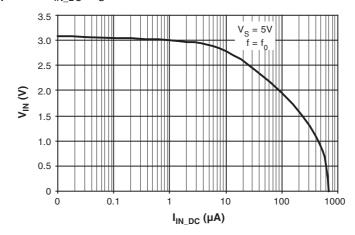


Figure 7-5. Data Transmission Rate, $V_S = 3V$

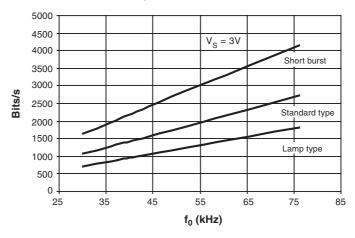


Figure 7-6. Data Transmission Rate, $V_S = 5V$

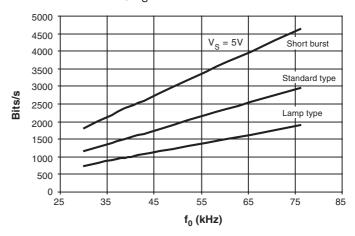
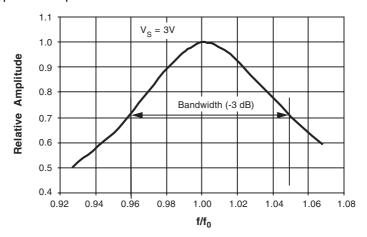


Figure 7-7. Typical Bandpass Curve



 $Q = f/f_0/B$; B => -3 dB values.

Example: Q = 1/(1.047 - 0.954) = 11

Figure 7-8. Illustration of Used Terms

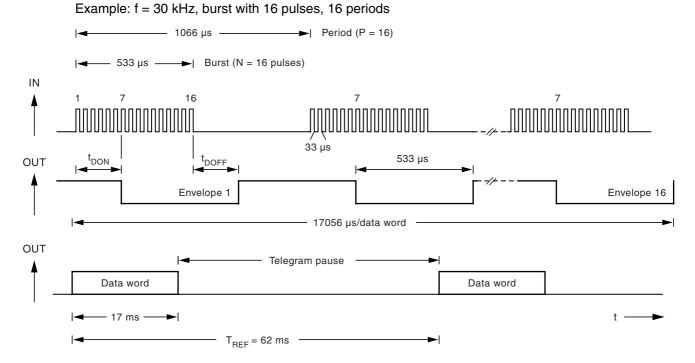






Figure 7-9. Test Circuit

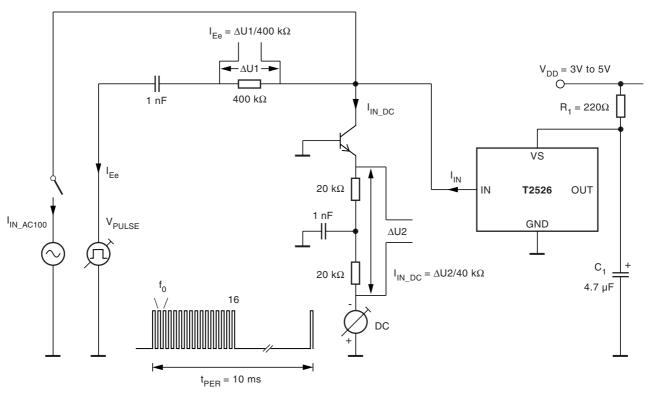
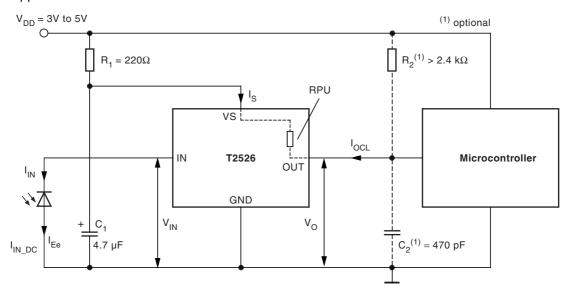
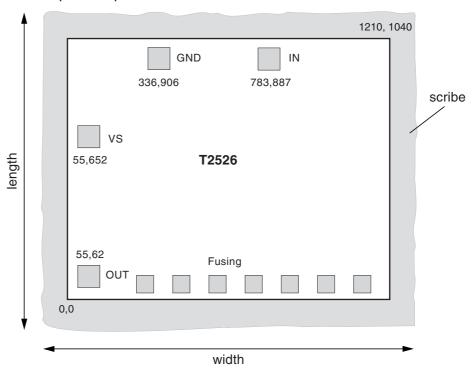


Figure 7-10. Application Circuit



8. Chip Dimensions

Figure 8-1. Chip Size in μm



Note: Pad coordinates are given for lower left corner of the pad in μm from the origin 0,0

Dimensions	Length inclusive scribe	1.16 mm
	Width inclusive scribe	1.37 mm
	Thickness	290 μ ± 5%
	Pads	$90~\mu\times90~\mu$
	Fusing pads	$70~\mu\times~70~\mu$
Pad metallurgy	Material	AlCu/AlSiTi ⁽¹⁾
	Thickness	0.8 µm
Finish	Material	$\mathrm{Si_3N_4/SiO_2}$
	Thickness	0.7/0.3 μm

Note: 1. Value depends on manufacture location.



9. Ordering Information

Delivery: unsawn wafers (DDW) in box

Extended Type Number	PL ⁽²⁾	R _{PU} ⁽³⁾	D ⁽⁴⁾	Type ⁽⁵⁾	
T2526N0xx ⁽¹⁾ -DDW	2	30	2179	Ctandard tune: > 10 pulses, appeared cancibility bigh data rate	
T2526N1xx ⁽¹⁾ -DDW	1	30	2179	Standard type: ≥ 10 pulses, enhanced sensibility, high data rate	
T2526N2xx ⁽¹⁾ -DDW	2	40	1404	Lamp type: ≥ 10 pulses, enhanced suppression of disturbances, secure	
T2526N3xx ⁽¹⁾ -DDW	1	40	1404	data transmission	
T2526N6xx ⁽¹⁾ -DDW	2	30	3415	Chart hund trues > Caulose anhanced data rate	
T2526N7xx ⁽¹⁾ -DDW	1	30	3415	Short burst type: ≥ 6 pulses, enhanced data rate	

Notes:

- 1. xx means the used carrier frequency value f₀ 30, 33, 36, 38, 40, 44 or 56 kHz (76 kHz type on request)
- 2. Two pad layout versions (see Figure 9-1 and Figure 9-2) available for different assembly demand
- 3. Integrated pull-up resistor at pin OUT (see electrical characteristics)
- 4. Typical data transmission rate up to bit/s with $f_0 = 56$ kHz, $V_S = 5$ V (see Figure 7-8 on page 9)
- 5. On request: noise type, data rate type

9.1 Pad Layout

Figure 9-1. Pad Layout 1

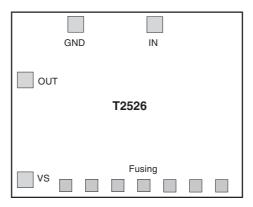
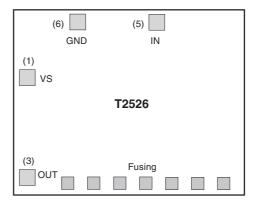


Figure 9-2. Pad Layout 2



10. Revision History

Please note that the following page numbers referred to in this section refer to the specific revision mentioned, not to this document.

Revision No.	History					
	Features on page 1 changed					
	Applications on page 1 changed					
	Section 1 "Description" on page 1 changed					
4597G-AUTO-10/06	 Section 5 "Electrical Characteristics, 3-V Operation" number 3.4 on page 3 changed 					
	 Section 6 "Electrical Characteristics, 5-V Operation" number 7.3 and 7.4 on page 5 changed 					
	 Section 9 "Ordering Information" on page 11 changed 					
4597F-AUTO-04/06	Section 9 "Ordering Information" on page 11 changed					
4507F AUTO 04/06	Put datasheet in a new template					
4597E-AUTO-04/06	Section 8 "Chip Dimensions" on page 10 changed					
	Put datasheet in a new template					
4597D-AUTO-08/05	First page: Pb-free logo added					
4087 D-AUTO-00/00	Page 11: Ordering Information changed					
	• Page 2, 3, 5, 11, 13: SO8 deleted					





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